

**WIAS-HITNIHS: A SOFTWARE TOOL FOR SIMULATION IN
SUBLIMATION GROWTH OF SiC SINGLE CRYSTALS:
APPLICATIONS AND METHODS. ***

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Abstract. The numerous technical applications in electronic and optoelectronic devices, such as lasers, diodes, and sensors demand high-quality silicon carbide (SiC) bulk single crystal for industrial applications. We consider a SiC crystal growth process by physical vapor transport (PVT), called modified Lely method. We deal with a model for the thermal processes within the growth apparatus, involving a heat equation with heat sources due to induction heating and nonlocal interface conditions, representing the heat transfer by radiation. The study of the temperature evolution in the apparatus is important for understanding and optimizing the crystal growth process. We present results of some numerical simulations of the growth apparatus with respect to grid refinements and discuss numerical errors in the simpler stationary case.

Keywords: numerical methods, heat equation, radiation, crystal growth process, numerical simulations, stationary case.

1. Introduction and mathematical model. The motivation for this study comes from the technical demand to simulate a crystal growth apparatus for SiC single crystals. The single crystals are used as a high-valued and expensive material for optoelectronics and electronics, cf. [8]. The silicon carbide (SiC) bulk single crystal are produced by a growth process through physical vapor transport (PVT), called modified Lely-method. The modeling for the thermal processes within the growth apparatus is done in [4] and [10]. The underlying equations of the model are given as follows:

a.) In this work, we assume that the temperature evolution inside the gas region Ω_g can be approximated by considering the gas as pure argon. The reduced heat equation is

$$\rho_g \partial_t U_g - \nabla \cdot (\kappa_g \nabla T) = 0, \quad (1.1)$$

$$U_g = z_{Ar} R_{Ar} T, \quad (1.2)$$

where T is the temperature, t is the time, and U_g is the internal energy of the argon gas. The parameters are given as ρ_g being the density of the argon gas, κ_g being the thermal conductivity, z_{Ar} being the configuration number, and R_{Ar} being the gas constant for argon.

b.) The temperature evolution inside the region of solid materials Ω_s , e.g. inside the silicon carbide crystal, silicon carbide powder, graphite, and graphite insulation, is described by the heat equation

$$\rho_s \partial_t U_s - \nabla \cdot (\kappa_s \nabla T) = f, \quad (1.3)$$

$$U_s = \int_0^T c_s(S) dS, \quad (1.4)$$

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where ρ_s is the density of the solid material, U_s is the internal energy, κ_s is the thermal conductivity, and c_s is the specific heat.

The equations hold in the domains of the respective materials and are coupled by interface conditions, e.g. requiring the continuity for the temperature and for the normal components of the heat flux on the interfaces between opaque solid materials. On the boundary of the gas domain, i.e. on the interface between the solid material and the gas domain, we consider the interface condition

$$\kappa_g \nabla T \cdot \mathbf{n}_g + R - J = \kappa_s \nabla T \cdot \mathbf{n}_g, \quad (1.5)$$

where \mathbf{n}_g is the normal vector of the gas domain, R is the radiosity, and J is the irradiosity. The irradiosity is determined by integrating R along the whole boundary of the gas domain, cf. [7]. Moreover, we have

$$R = E + J_{\text{ref}}, \quad (1.6)$$

$$E = \sigma \epsilon T^4 \quad (\text{Stefan-Boltzmann equation}), \quad (1.7)$$

$$J_{\text{ref}} = (1 - \epsilon) J, \quad (1.8)$$

where E is the radiation, J_{ref} is the reflexed radiation, ϵ is the emissivity, and σ is the Boltzmann radiation constant.

The density of the heat source induced by the induction heating is determined by solving Maxwell's equations. We deal with these equations under the simplifying assumption of an axisymmetric geometry, axisymmetric electromagnetic fields, and a sinusoidal time dependence of the involved electromagnetic quantities, following [12]. The considered system and its derivation can be found in [4], [6], and [10].

In this paper, we focus on the discretization and material properties, which are important for realistic simulations. Our underlying software tool WIAS-HiTNIHS, cf. [10], allows us flexibility in the grid generation and for the material parameters.

In the next section, we describe the used discretization.

2. Discretization. For the discretization of the heat equation (diffusion equation), we apply the implicit Euler method in time and the finite volume method for the space discretization, cf. [2], [4], and [10]. We consider a partition $\mathcal{T} = (\omega_i)_{i \in I}$ of Ω such that, for $m \in \{s, g\}$ (with s solid, g gas) and $i \in I$, $\omega_{m,i} := \omega_i \cap \Omega_m$ defines either a void subset or a nonvoid, connected, and open polyhedral subset of Ω . By integrating the corresponding heat equation (1.1) or (1.3) over $\omega_{m,i}$, we derive the following nonlinear equations for the temperature variables,

$$\begin{aligned} \rho_m \int_{\omega_{m,i}} (U_m(T^{n+1}) - U_m(T^n)) r \, dx \\ - \Delta t^{n+1} \int_{\partial \omega_{m,i}} \kappa_m(T^{n+1}) \nabla T^{n+1} \cdot \mathbf{n}_{\omega_{m,i}} r \, ds = \Delta t^{n+1} \int_{\omega_{m,i}} f_m r \, dx, \end{aligned} \quad (2.1)$$

where the time interval is $\Delta t^{n+1} = t^{n+1} - t^n$. The temperature is given as $T^{n+1} = T(t^{n+1}, x)$, where x represents cylindrical coordinates. For the right-hand sides, we demand $f_s := f \geq 0$ and $f_g = 0$.

More details of the discretization and of dealing with the interface conditions are presented in [3], [4], [5], and [10].

In the next section, the properties of the materials in the crystal growth apparatus are described.

3. Material properties. For the technical realization of the apparatus, we implement the axisymmetric geometry given in [11], which is presented in Fig. 3.1. Furthermore, the properties of the materials are specified in [3], [4], and [9].

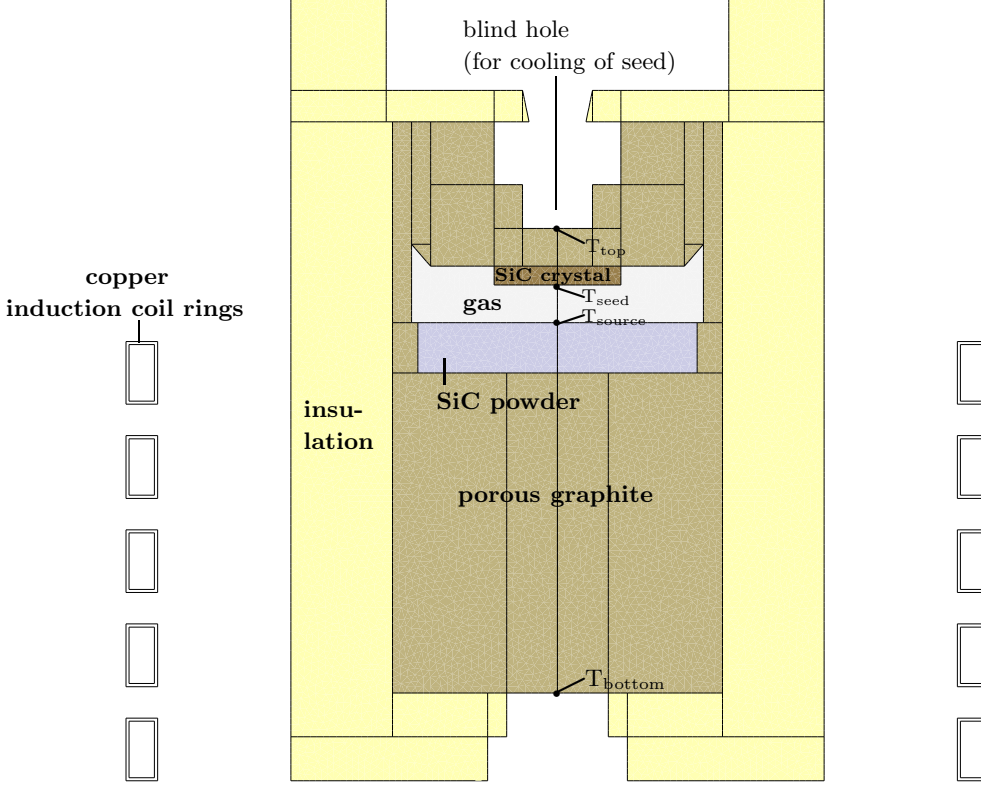


FIG. 3.1. *The growth apparatus' dimensions: $r_{min} = 0$, $r_{max} = 8.4$ cm, $z_{min} = 0$, $z_{max} = 25.0$ cm, the coil rings' dimensions: $r_{min} = 4.2$ cm, $r_{max} = 5.2$ cm, $z_{min} = 0$, $z_{max} = 14.0$ cm.*

Within the following specific material functions and parameters for the processes, the thermal conductivity κ is given in W/(m K), the electrical conductivity σ_c is given in 1/(Ohm m), the mass density ρ is given in kg/m³, the specific heat c_{sp} is given in J/(K kg), the temperature T is given in K and the relative gas constant R_{Ar} is given in J/(K kg). Further the emissivity ϵ and relative magnetic permeability μ are given dimensionless.

For the gas phase (argon), we have

$$\kappa_{Ar}(T) = \begin{cases} 1.83914 \cdot 10^{-4} T^{0.800404} & T \leq 500, \\ -7.128738 + 6.610288 \cdot 10^{-2} T - 2.440839 \cdot 10^{-4} T^2 & 500 \leq T \leq 600, \\ +4.497633 \cdot 10^{-7} T^3 - 4.132517 \cdot 10^{-10} T^4 + 1.514463 \cdot 10^{-13} T^5 & 600 \geq T, \\ 4.1944 \cdot 10^{-4} T^{0.671118} & \end{cases}$$

$$\sigma_{c,Ar} = 0.0, \rho_{Ar} = 3.73 \cdot 10^{-3}, \mu_{Ar} = 1.0, z_{Ar} = 3/2, R_{Ar} = 2.081308 \cdot 10^{-2}.$$

For graphite felt insulation, we have

$$\kappa_{Ins}(T) = \begin{cases} 8.175 \cdot 10^{-2} + 2.485 \cdot 10^{-4} T & T \leq 1473, \\ -1.1902 \cdot 10^2 + 0.346838 T - 3.9971 \cdot 10^{-4} T^2 + 2.2830 \cdot 10^{-7} T^3 & 1473 \leq T \leq 1873, \\ -6.46047 \cdot 10^{-11} T^4 + 7.2549 \cdot 10^{-15} T^5 & 1873 \geq T, \\ -0.7447 + 7.5 \cdot 10^{-4} T & \end{cases}$$

$\epsilon_{\text{Ins}} = 0.2$, $\sigma_{c,\text{Ins}}(T) = 2.45 \cdot 10^2 + 9.82 \cdot 10^{-2} T$, $\rho_{\text{Ins}} = 170.00$, $\mu_{\text{Ins}} = 1.00$,
 $c_{\text{sp,Ins}} = 2100.00$.

For the graphite, we have

$\kappa_{\text{Graphite}}(T) = 37.715 \exp(-1.96 \cdot 10^{-4} T)$,

$$\epsilon_{\text{Graphite}}(T) = \begin{cases} 0.67 & T \leq 1200, \\ 3.752 - 7.436 \cdot 10^{-3} T + 6.4163 \cdot 10^{-6} T^2 & 1200 \leq T \leq 2200, \\ -2.3366 \cdot 10^{-9} T^3 - 3.0833 \cdot 10^{-13} T^4 & 2200 \geq T, \\ 0.79 & \end{cases}$$

$\sigma_{c,\text{Graphite}} = 10^4$, $\rho_{\text{Graphite}} = 1750.0$, $\mu_{\text{Graphite}} = 1.0$,
 $c_{\text{sp,Graphite}}(T) = 1/(4.411 \cdot 10^2 T^{-2.306} + 7.97 \cdot 10^{-4} T^{-0.0665})$.

For the SiC crystal, we have

$\kappa_{\text{SiC-C}}(T) = \exp(9.892 + (2.498 \cdot 10^2)/T - 0.844 \ln(T))$,
 $\epsilon_{\text{SiC-C}} = 0.85$, $\sigma_{c,\text{SiC-C}} = 10^5$, $\rho_{\text{SiC-C}} = 3140.0$, $\mu_{\text{SiC-C}} = 1.0$,
 $c_{\text{sp,SiC-C}}(T) = 1/(3.91 \cdot 10^4 T^{-3.173} + 1.835 \cdot 10^{-3} T^{-0.117})$.

For the SiC powder, we have

$\kappa_{\text{SiC-P}}(T) = 1.452 \cdot 10^{-2} + 5.47 \cdot 10^{-12} T^3$,
 $\epsilon_{\text{SiC-P}} = 0.85$, $\sigma_{c,\text{SiC-P}} = 100.0$, $\rho_{\text{SiC-P}} = 1700.0$, $\mu_{\text{SiC-P}} = 1.0$, $c_{\text{sp,SiC-P}} = 1000.0$.

The functions are programmed in our flexible software package WIAS-HiTNIHS. In the next section, we present results of our numerical experiments.

4. Numerical experiments. For the numerical results, we apply the parameter functions in Section 3. We consider the geometry shown in Fig. 3.1, using a constant total input power of 10 kW, cf. [11]. The numerical experiments are performed using the software WIAS-HiTNIHS, cf. [10], based on the software package *pdelib*, cf. [1], which uses the sparse matrix solver *PARDISO*, cf. [13]. We compute the coupled system consisting of the heat equations and Maxwell's equations. For the growth process, the temperature difference $T_{\text{ss}} = T(r_{\text{source}}, z_{\text{source}}) - T(r_{\text{seed}}, z_{\text{seed}})$ (with the coordinates $(r_{\text{source}}, z_{\text{source}}) = (0, 0.143)$ and $(r_{\text{seed}}, z_{\text{seed}}) = (0, 0.158)$, corresponding to the points T_{source} and T_{seed} in Fig. 3.1) is crucial. On the other hand, in the physical growth experiments, usually only the temperatures $T(r_{\text{bottom}}, z_{\text{bottom}})$ and $T(r_{\text{top}}, z_{\text{top}})$ (with the coordinates $(r_{\text{bottom}}, z_{\text{bottom}}) = (0, 0.028)$ and $(r_{\text{top}}, z_{\text{top}}) = (0, 0.173)$, corresponding to the points T_{bottom} and T_{top} in Fig. 3.1) are measurable and their difference $T_{\text{bt}} = T(r_{\text{bottom}}, z_{\text{bottom}}) - T(r_{\text{top}}, z_{\text{top}})$ is often used as an indicator for T_{ss} . In Fig. 4.1, we present the temperature differences T_{ss} and T_{bt} . As a result of our computations, the temperature difference T_{bt} can only restrictively be used as an indicator for the temperature difference T_{ss} , cf. the discussions in [3] and [7].

The further computations are based on the stationary case, dealing with Equation (1.1) by discarding the terms with a time derivative. For this case, the results are virtually equal to the one in the transient case with $t > 15000$ sec. For the stationary results, we focus on the error analysis for the space dimension by applying the grid refinement. The solutions for the heat equation are computed at the points $T(r_{\text{bottom}}, z_{\text{bottom}})$ and $T(r_{\text{top}}, z_{\text{top}})$ for successive grids. For the error analysis, we apply the following error differences

$$\epsilon_{\text{abs}} = |\tilde{T}_{j+1}(r, z) - \tilde{T}_j(r, z)|, \quad (4.1)$$

where $\tilde{T}_j(r, z)$ and $\tilde{T}_{j+1}(r, z)$ are solutions evaluated at the point (r, z) which have been computed using the grids j and $j + 1$ respectively. The elements of the grid

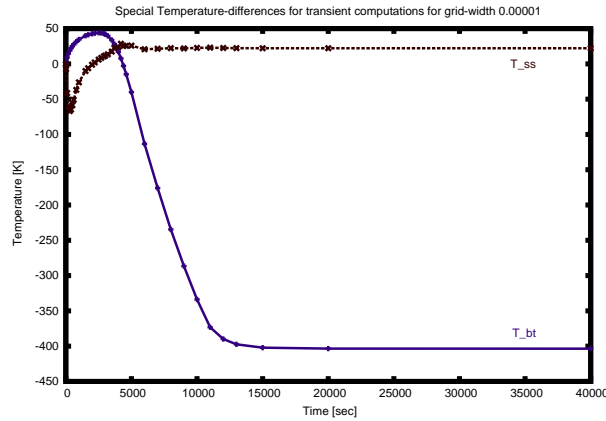


FIG. 4.1. Transient results for the temperature differences T_{bt} and T_{ss} .

$j + 1$ are approximately 1/4 of the elements of the grid j . The results are presented in Table 4.1.

Grid		Grid Point (0, 0.028) (T_{bottom})		Grid Point (0, 0.173) (T_{top})	
Level	Number of Nodes	Solution T [K]	Absolute Difference T [K]	Solution T [K]	Absolute Difference T [K]
0	1532	2408.11		2813.29	
1	23017	2409.78	1.67	2812.78	1.01
2	91290	2410.35	0.57	2811.79	0.49
3	364225	2410.46	0.11	2811.60	0.19

TABLE 4.1

Computations on different grids for the errors analysis with absolute differences, cf. (4.1).

The result of the refinement indicates the reduction of the absolute difference as it is demanded for the convergence of the discretization method. The method is stabilized in the presented refinement by reducing the differences.

In Fig. 4.2, the temperature field is presented for the stationary case. The temperature increases from the bottom to the middle of the graphite pot, and decreases from the middle to the top of the graphite pot.

In the next section, we present the conclusion of our simulations.

5. Conclusion. We have presented a model for the heat transport inside a technical apparatus for crystal growth of SiC single crystals. We introduce the heat equation and the radiation of the apparatus and the coupled situation of the different materials. The equations are discretised by the finite volume method and the complex material functions are embedded in this method. Transient and stationary results are presented leading to some information about the processes within the technical apparatus. We present numerical results for the stationary case to support the accuracy of our solutions. In our future work, we concentrate on further implementations and numerical methods for a crystal growth model.

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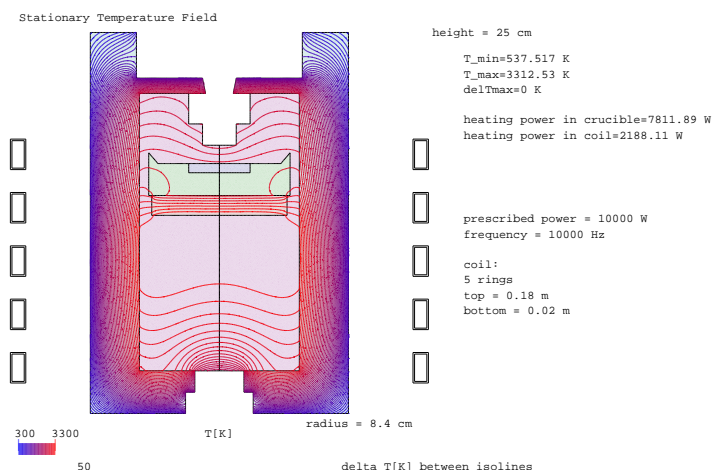


FIG. 4.2. Temperature field for the apparatus simulated for the stationary case with 23017 nodes.

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